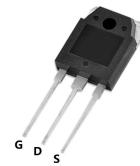


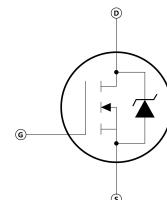
Features

- Low gate charge
- Low Crss (typical 13pF)
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability



Applications

- High efficiency switch mode power supplies
- Electronic lamp ballasts based on half bridge
- LED power supplies



Absolute Ratings (Tc=25°C)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V _{DSS}	1000	V
Drain Current -continuous	I _D	10	A
	T=25°C T=100°C	6.0*	A
Drain Current - pulse (note 1)	I _{DM}	36	A
Gate-Source Voltage	V _{GSS}	±30	V
Single Pulsed Avalanche Energy (note 2)	E _{AS}	858	mJ
Avalanche Current (note 1)	I _{AR}	10	A
Repetitive Avalanche Current (note 1)	E _{AR}	27.7	mJ
Peak Diode Recovery dv/dt (note 3)	dv/dt	4.1	V/ns
Power Dissipation	PD	186.5	W
	TC=25°C Derate above 25°C	1.492	W/°C
Operating and Storage Temperature Range	T _J , T _{STG}	-55~+150	°C
Maximum Lead Temperature for Soldering Purposes	T _L	300	°C

Electrical Characteristics($T_{CASE}=25^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	Tests conditions	Min	Typ	Max	Units
Off-Characteristics						
Drain-Source Voltage	BV_{DSS}	$I_D=250\mu\text{A}, V_{GS}=0\text{V}$	1000	-	-	V
Breakdown Voltage Temperature Coefficient Zero Gate Voltage Drain Current	$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	$I_D=250\mu\text{A}, \text{referenced to } 25^{\circ}\text{C}$	-	0.98	-	$\text{V}/^{\circ}\text{C}$
		$V_{DS}=900\text{V}, V_{GS}=0\text{V}, T_C=25^{\circ}\text{C}$	-	-	1	μA
		$V_{DS}=720\text{V}, T_C=125^{\circ}\text{C}$	-	-	10	μA
Gate-body leakage current, forward	I_{GSSF}	$V_{DS}=0\text{V}, V_{GS}=30\text{V}$	-	-	100	nA
Gate-body leakage current, reverse	I_{GSSR}	$V_{DS}=0\text{V}, V_{GS}=30\text{V}$	-	-	-100	nA
On-Characteristics						
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	3	-	5	V
Static Drain-Source On-Resistance	$R_{DS(\text{ON})}$	$V_{GS}=10\text{V}, I_D=4.5\text{A} 25^{\circ}\text{C}$	-	2.37	2.8	Ω
		$V_{GS}=10\text{V}, I_D=4.5\text{A} 100^{\circ}\text{C}$	-	3.37	3.9	Ω
		$V_{GS}=10\text{V}, I_D=4.5\text{A} 150^{\circ}\text{C}$	-	9.5	-	S
Forward Transconductance	g_{fs}	$V_{DS}=40\text{V}, I_D=4.5\text{A} (\text{note 4})$	-	1200	2150	pF
Dynamic Characteristics						
Gate resistance	R_g	$F=1.0\text{MHZ}$ open drain	0.5	-	3	Ω
Input capacitance	C_{iss}	$V_{DS}=25\text{V}, V_{GS}=0\text{V}, I=1.0\text{MHZ}$	100	189	246	pF
Output capacitance	C_{oss}		5	13	17	pF
Reverse transfer capacitance	C_{rss}		-	-	-	-

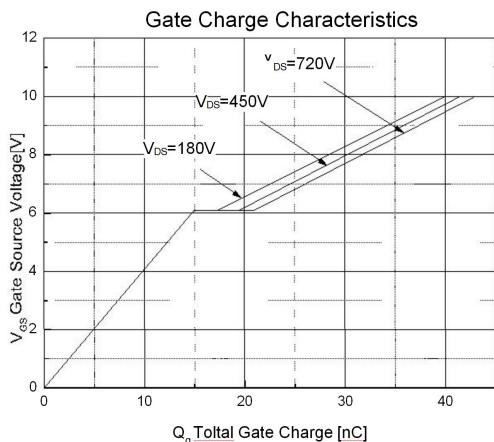
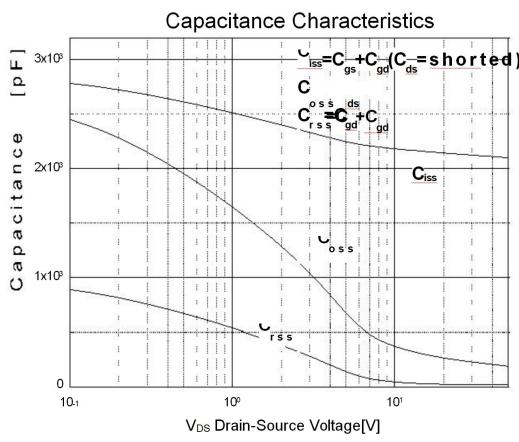
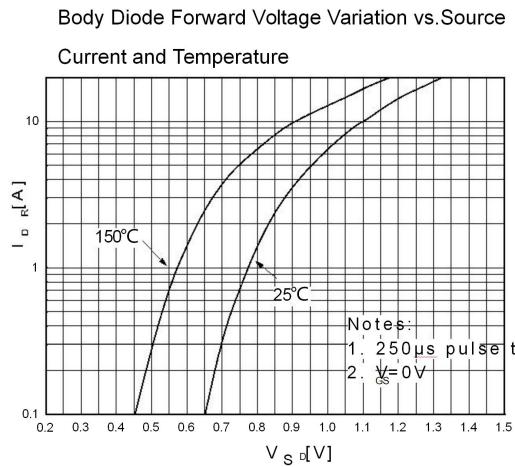
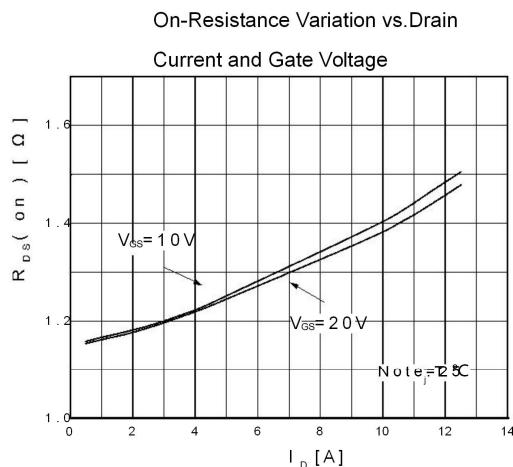
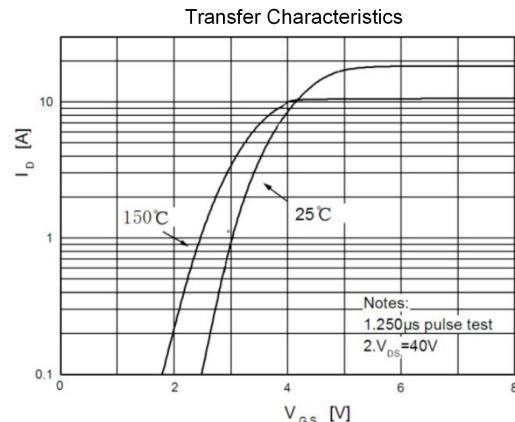
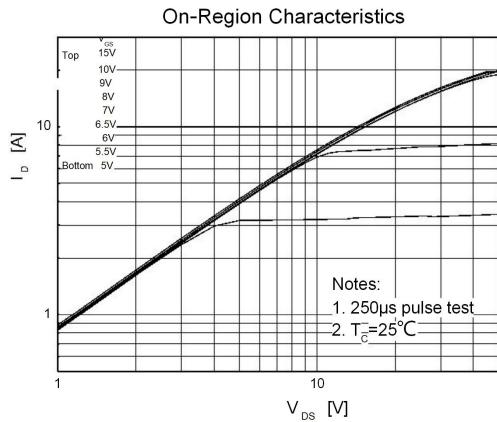
Switching Characteristics							
Turn-On delay time	td(on)	VDD=450V, ID=9A, RG =25Ω(note 4,5)	-	53	121	ns	
Turn-On rise time	tr		-	116	235	ns	
Turn-Off delay time	td(off)		-	97	199	ns	
Turn-Off Fall time	tf		-	69	171	ns	
Total Gate Charge	Qg	V _{DS} =720V, I _D =9A, V _{GS} =10V(note4,5)	-	43	56	nC	
Gate-Source charge	Qgs		-	15	40	nC	
Gate-Drain charge	Qgd		-	21	50	nC	
Drain-Source Diode Characteristics and Maximum Ratings							
Maximum Continuous Drain -Source Diode Forward Current	Is		-	-	10	A	
Maximum Pulsed Drain-Source Diode Forward Current	ISM		-	-	36	A	
Drain-Source Diode Forward Voltage	VSD	V _{GS} =0V, IS=9A	-	-	1.4	V	
Reverse recovery time	trr	V _{GS} =0V, IS=9A dIF/dt=100A/us(note 4)	-	539	1200	ns	
Reverse recovery charge	Qrr		-	6.41	12	uC	

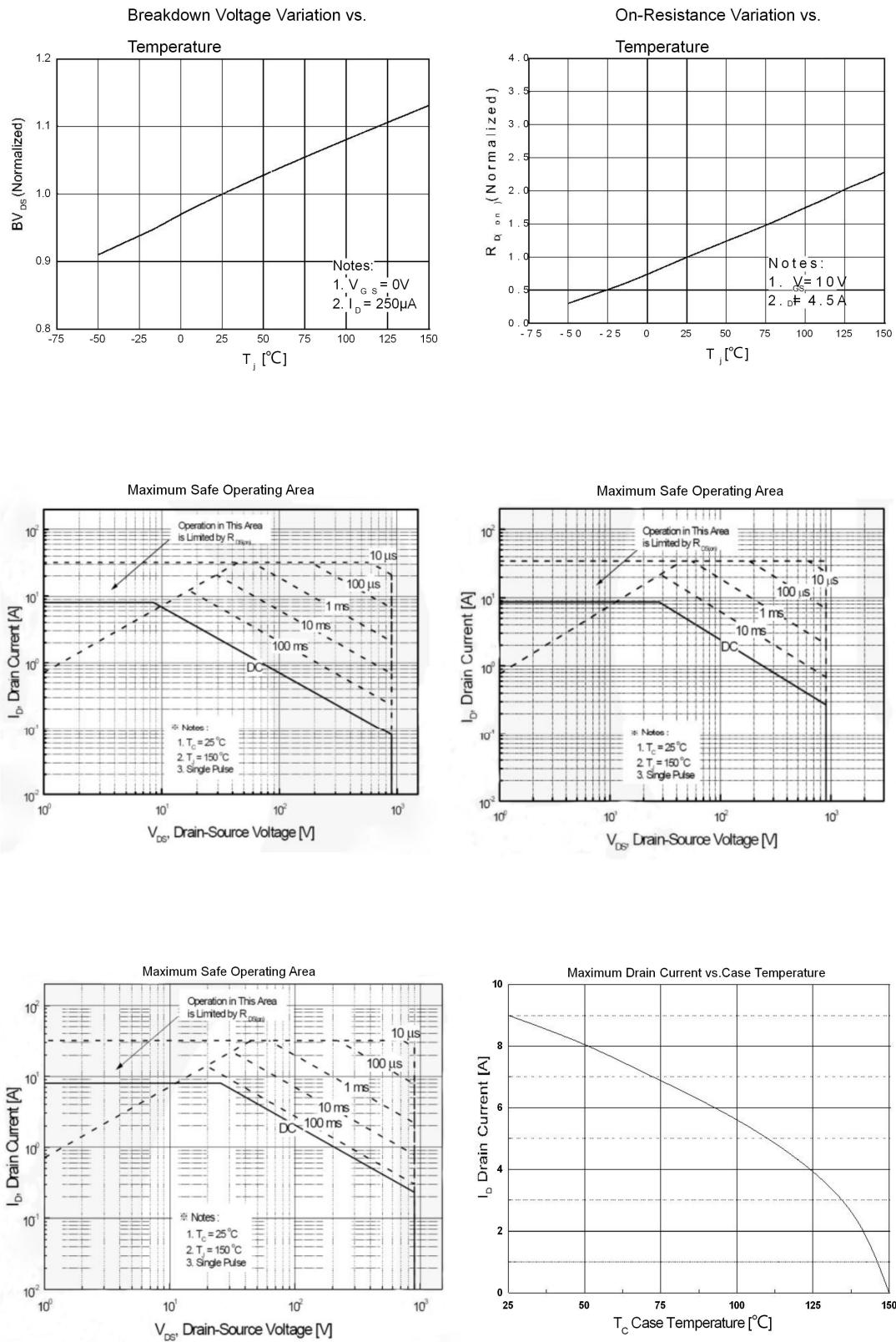
Parameter	Symbol	Value	Unit
Thermal Resistance, Junction to Case	R _{th(j-c)}	0.67	°C/W
Thermal Resistance, Junction to Ambient	R _{th(j-A)}	40	°C/W

Notes:

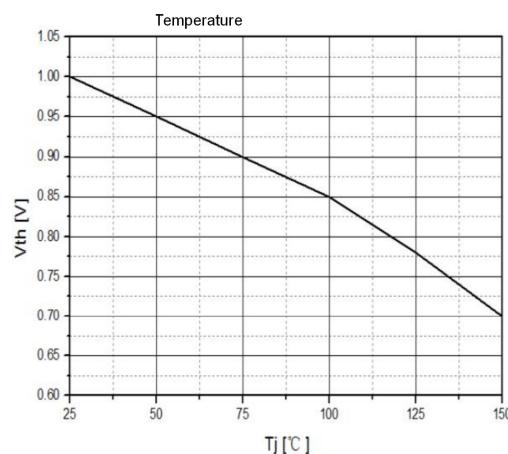
- 1:Pulse width limited by maximum junction temperature
- 2:L=20mH,I_{AS}=10A,V_{DD}=50V,R_G=25Ω,Starting T_J=25°C
- 3:I_{SD}≤10A,di/dt≤200A/us,V_{DD}≤BV_{DSS},Starting T_J=25°C
- 4:Pulse Test:Pulse Width≤200us,Duty Cycle≤2%
- 5:Essentially independent of operating temperature

Electrical Characteristics

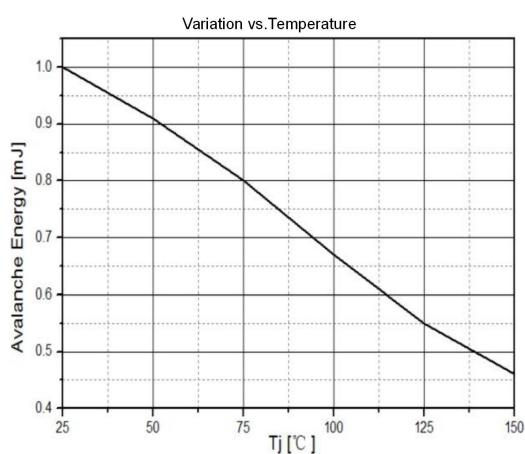




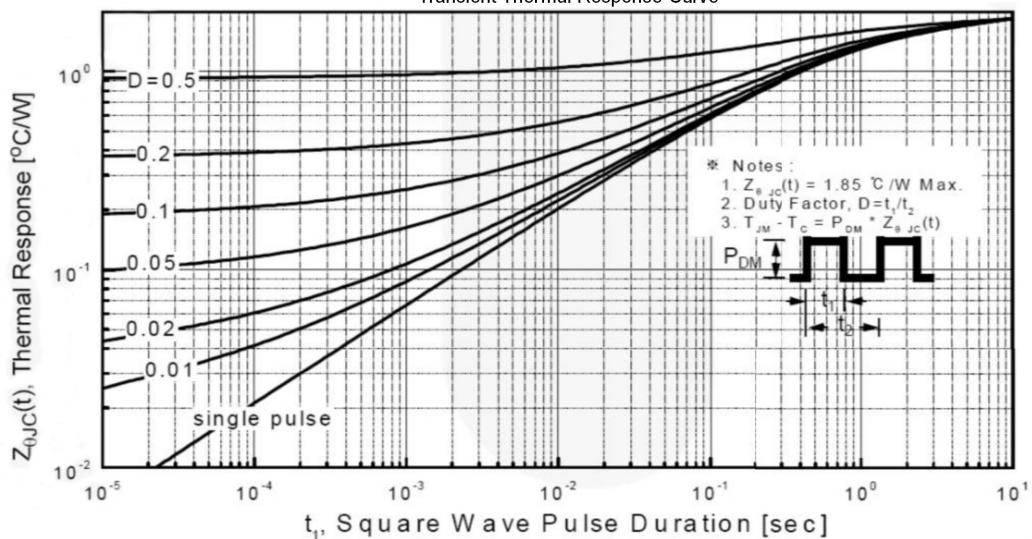
Gate Threshold Voltage Variation vs.



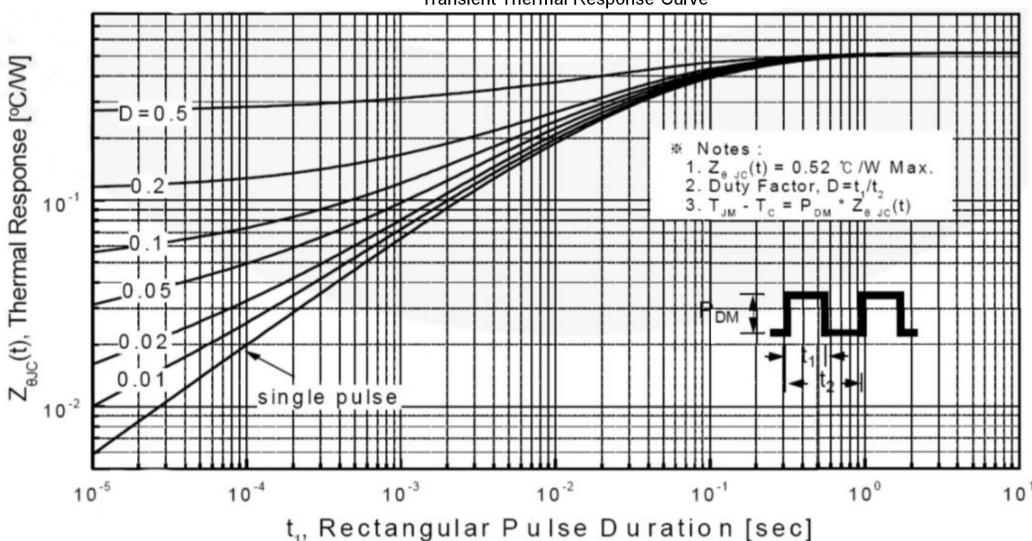
Single Pulsed Avalanche Energy

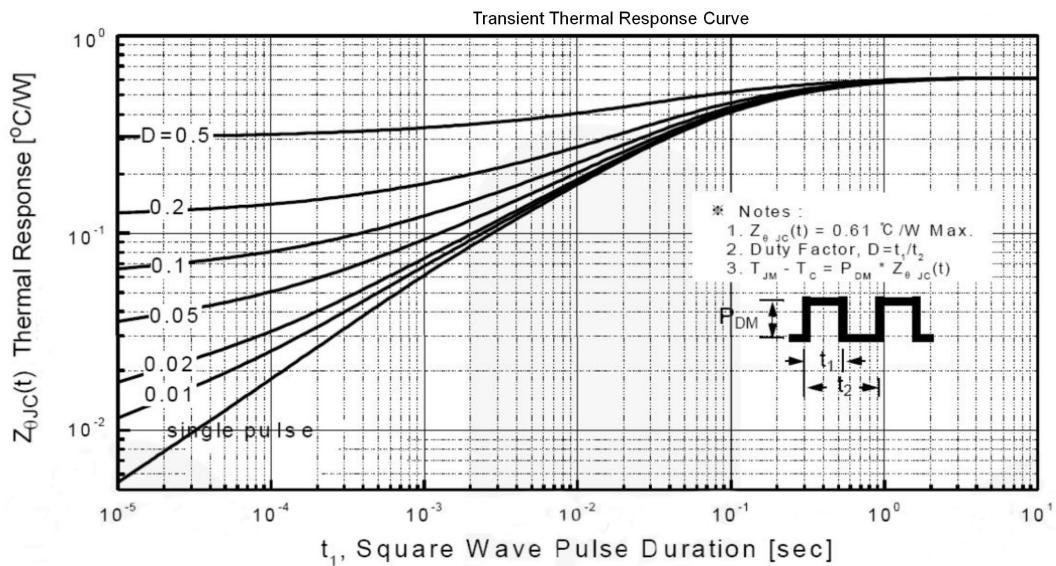


Transient Thermal Response Curve



Transient Thermal Response Curve





Package Mechanical DATA

